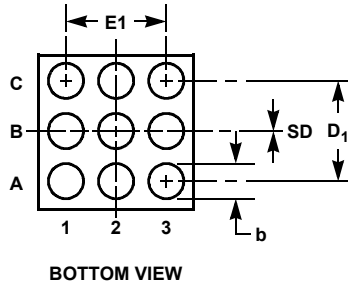
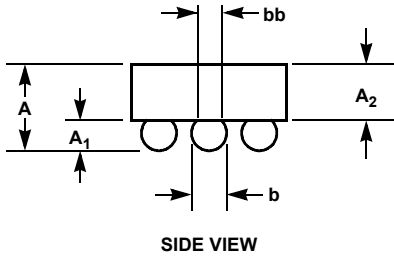
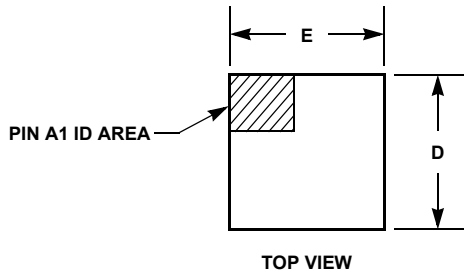


# Plastic Packages for Integrated Circuits

## Wafer Level Chip Scale Package (WLCSP)



### W3x3.9B

3x3 ARRAY 9 BALL WAFER LEVEL CHIP SCALE PACKAGE  
(Renesas Standard)

SYMBOL	MILLIMETERS	NOTES
A	0.54 Min, 0.65 Max	-
A <sub>1</sub>	0.24 ±0.03	-
A <sub>2</sub>	0.355 ±0.03	-
b	0.32 ±0.03	-
bb	∅ 0.30 REF.	-
D	1.45 ±0.05	-
D <sub>1</sub>	1.00 BASIC	-
E	1.45 ±0.05	-
E <sub>1</sub>	1.00 BASIC	-
e	0.50 BASIC	-
SD	0.00 BASIC	-
N	9	3

Rev. 0 6/06

#### NOTES:

1. Dimensions are in Millimeters.
2. Dimensioning and tolerancing conform to ASME 14.5M-1994.
3. Symbol "N" is the actual number of solder balls.
4. Reference JEDEC MO-211-C, variation DD.